1 Package summary

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<th>Max</th>
<th>Unit</th>
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<td>5</td>
<td>5.1</td>
<td>mm</td>
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<td>package width</td>
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<td>0.85</td>
<td>0.9</td>
<td>mm</td>
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<td>nominal pitch</td>
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<td>0.5</td>
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<td>mm</td>
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<tr>
<td>actual quantity of termination</td>
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<td>32</td>
<td>-</td>
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</table>
2 Package outline

Figure 1. Package outline HVQFN32 (SOT617-24)
Figure 2. Package outline detail E of HVQFN32 (SOT617-24)
3 Soldering

Figure 3. Reflow soldering footprint part1 for HVQFN32 (SOT617-24)
Figure 4. Reflow soldering footprint part2 for HVQFN32 (SOT617-24)
Figure 5. Reflow soldering footprint part3 for HVQFN32 (SOT617-24)
H-PQFN-32 I/O
5 x 5 x 0.85 PKG, 0.5 PITCH

NOTES:
1. ALL DIMENSIONS ARE IN MILLIMETERS.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON–FUNCTIONAL PADS.
5. MIN. METAL GAP SHOULD BE 0.15 MM.
6. ANCHORING PADS.

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MECHANICAL OUTLINE
PRINT VERSION NOT TO SCALE
STANDARD: NON JEDEC
DRAWING NUMBER: 98ASA01550D
REVISION: 0
DATE: 30 OCT 2019

Figure 6. Package outline note of HVQFN32 (SOT617-24)
4 Legal information

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